



# EMC Compo 2013

## in Nara, Japan

December 15<sup>th</sup>– 18<sup>th</sup>, 2013

**CALL FOR PAPERS**

[www.emccompo2013.org](http://www.emccompo2013.org)

The achievements in terms of operating frequency and integration of semiconductor technology are constantly creating new challenges in EMC, which must necessarily be addressed at both the integrated circuit and system level. Keeping up-to-date is of paramount importance to be successful in this field. Following EMC Compo events in Angers, Munich, Torino, Toulouse and Dubrovnik, the 9<sup>th</sup> International Workshop **EMC Compo 2013** is intended to be a place for exchange of the latest research achievements and experience in IC-level EMC and it is addressed to researchers both from industry and from academia.

**EMC Compo 2013 in Nara, Japan** will be the first workshop to be held outside Europe. The workshop is focused on emission and susceptibility issues of digital, analogue and mixed-signal integrated circuits. The most recent advances in simulation and measurement techniques, models, standards, tools and design methodologies will be discussed. A Technical Exhibition will provide equipment manufacturers and suppliers an opportunity to display their products, services and to discuss them with potential clients.

### Topics

- Measurement and modeling of IC emission and susceptibility
- Signal Integrity and Power Integrity on IC and PCB-level
- EMC-aware IC Design and guidelines
- Tools to handle EMC at IC-level
- Computational electromagnetics for IC-level EMC
- EMC issues in System-on-Chip (SoC), System-in-Package (SiP), and 3D ICs
- EMC issues in smart power ICs
- EMC of ICs in wireless communications
- EMC of ICs for biomedical applications
- Materials for improved EMC of ICs
- Harsh environment effects on IC-level EMC
- Long-term electromagnetic robustness of ICs
- Standards and regulations up to 6 GHz
- Modern EMC education on IC-level EMC

### Paper Submission

Complete papers should be written in English and submitted in PDF format (max. 6 pages including title, 100 word abstract, illustrations and references), electronically through the website: [www.emccompo2013.org](http://www.emccompo2013.org), where further information on paper preparation is available.

**EMC Compo 2013** is organized by Kyoto University, and will be technically co-sponsored by **IEEE EMCS, EMCS Japan and Sendai chapters** (in process).

<b>Deadline for paper submission:</b>	<b>June 16, 2013</b>
<b>Notification of acceptance</b>	<b>: July 31, 2013</b>
<b>Final Paper due date</b>	<b>: September 23, 2013</b>
Information and Contact :	<a href="mailto:emccompo2013@cct.kuee.kyoto-u.ac.jp">emccompo2013@cct.kuee.kyoto-u.ac.jp</a>



### Workshop Venue: Todai-ji Cultural Center, in Todai-ji Temple

Japan's first international capital, Heijyo-kyo was set in Nara 710. Japanese ancient culture blended with various foreign cultures introduced through the Silk Road and it developed Japan's unique culture and spirit. **Nara** hosts 13 **World Heritage** temples, shrines and historical sites.

**EMC Compo 2013 in Nara** will be organized in conjunction with **EDAPS 2013, IEEE Electrical Design of Advanced Package & Systems Symposium, which will be held on Dec. 12-14 & 15, 2013 at the same venue.** A special joint workshop will be planned on Dec. 15<sup>th</sup>. Details of EDAPS at <http://www.edaps2013.org>





# EMC Compo 2013 in Nara, Japan

## Organizing Committee

### General chair:

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### Technical program co-chairs:

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Kouji Ichikawa, DENSO Corp.

### PhD session chair:

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### Tutorials chair:

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### Past conference chairs:

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## Technical Program Committee (tentative)

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Shih-Yi Yuan, Feng-Chia University

**Location of the Todai-ji Cultural Center :** The world famous Todai-ji Temple hosts various pavilions and halls, including many National Treasures. The Daibutsu-den Hall is the world's largest wooden structure, and the home of the popular Daibutsu or the Great Buddha (15meters tall and weighs approximately 250 tons). The Todaiji-Cultural Center was constructed in 2011 as a museum of Todai-ji Temple, and its Kinsho Hall can accomodates up to 321 people. The hall is within walking distance from many historical shrines and temples including World Heritage Sites.



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